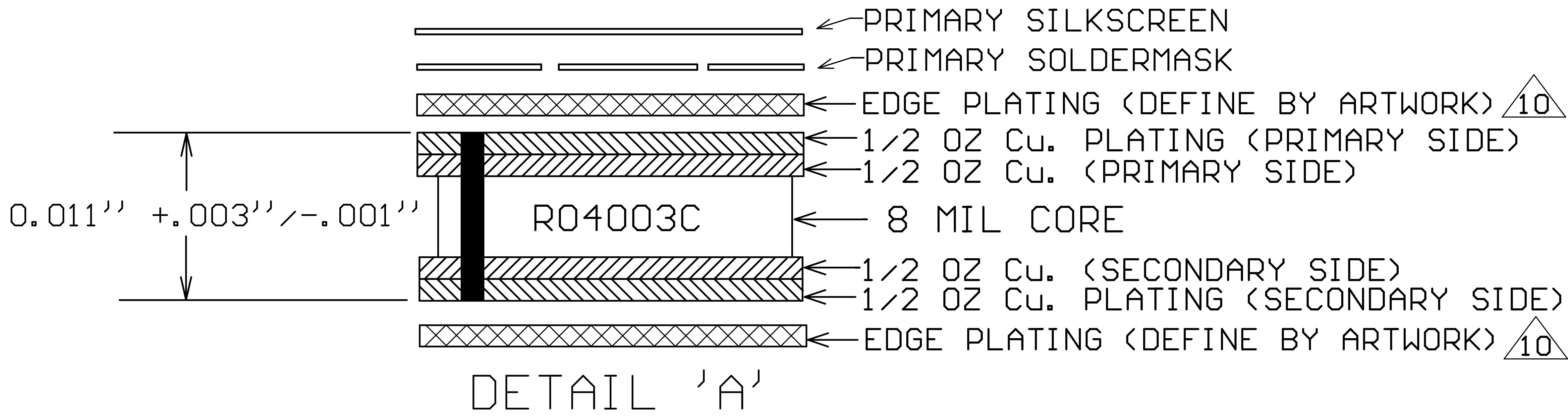


BOARD DIELECTRIC / COPPER STACKUP
FINISHED BOARD THICKNESS
(EXCLUDING PRIMARY SILKSCREEN & SOLDERMASK)

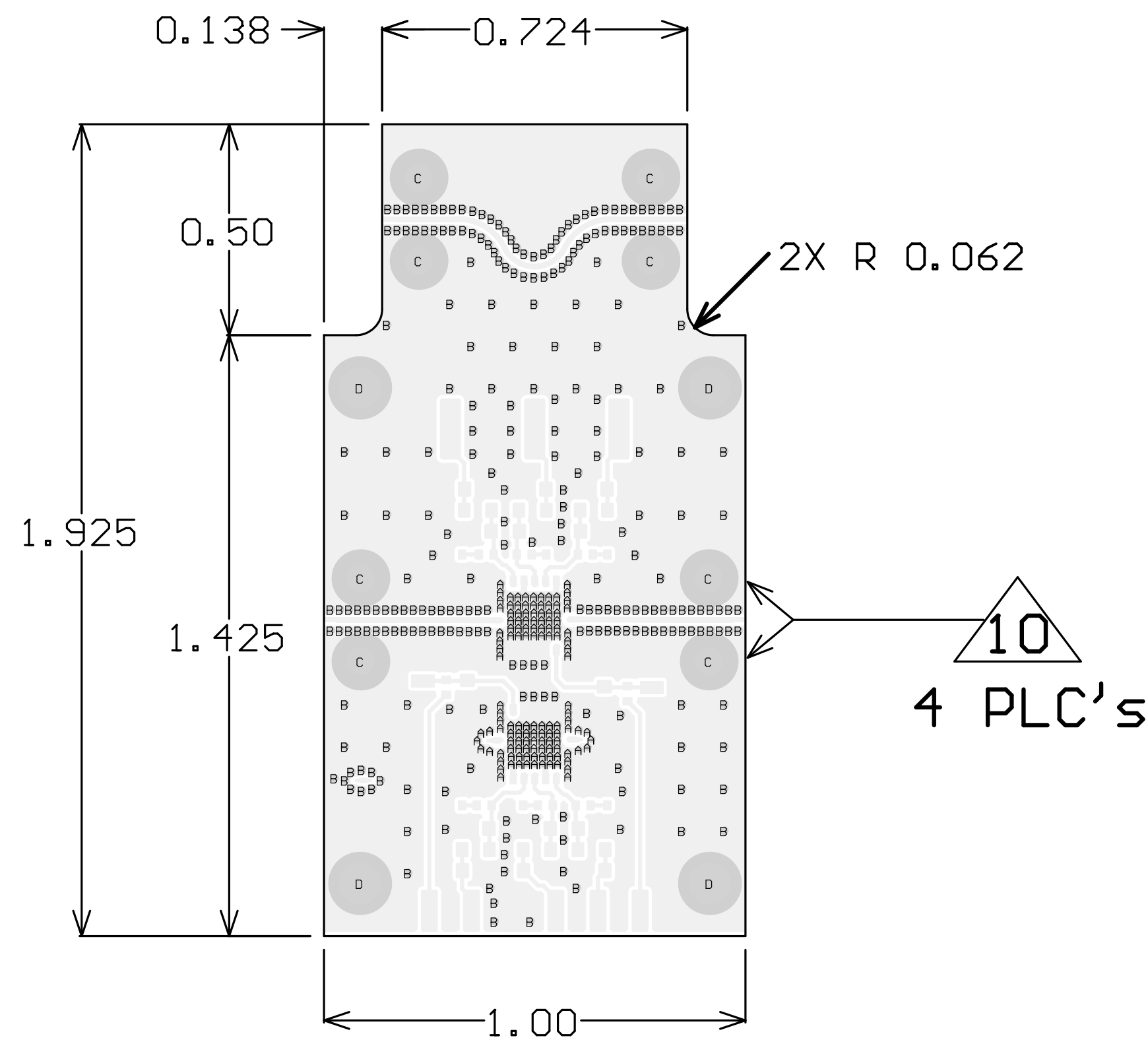


Symbol	Hit Count	FHS	Tol.	Plated	Hole Type	Drill Layer Pair
A	126	8.00mil	+3/-8mil	PTH	Round	Top Layer - Bottom Layer
B	258	10.00mil	+3/-10mil	PTH	Round	Top Layer - Bottom Layer
C	8	67.00mil	+/- 3mil	PTH	Round	Top Layer - Bottom Layer
D	4	100.00mil	+/- 3mil	PTH	Round	Top Layer - Bottom Layer
396 Total						

NOTES:

- MATERIAL:
R04003C 8 MIL DIELETRIC THICKNESS. SEE DETAIL 'A'
STARTING COPPER FOIL ON PRIMARY AND SECONDARY LAYERS SHALL BE 1/2 OZ.
COPPER ON PRIMARY AND SECONDARY SHALL BE PLATED UP AN ADDITIONAL 1/2 OZ.
MATERIAL STACKUP, THICKNESS, AND STARTING COPPER FOIL PER DETAIL 'A'.
- FINISH: PRIMARY AND SECONDARY SIDE FINISH;
ELECTROLESS NICKEL/IMMERSION GOLD (ENIG) PER IPC-4552 LATEST REVISION.
THERE SHALL BE NO PITS, PIN HOLES, SCRATCHES OR NODULES WITHIN EXPOSED METAL AREAS
SHALL PASS SOLDERABILITY TESTING PER IPC-J-STD-003 LATEST REVISION.
- PCB SHALL BE FABRICATED PER IPC-6012 CLASS 2 AND CONFORM TO IPC-A-600 CLASS 2 LATEST REVISIONS.
- ALL HOLES TO BE PLATED THRU UNLESS OTHERWISE SPECIFIED.
ALL FINISHED DRILL HOLE SIZES APPLY AFTER PLATING.
COPPER PLATING IN THROUGH HOLES WILL BE 0.001'' AVERAGE WITH AN
ABSOLUTE MINIMUM OF 0.0007''.

- ALL 8 FHS SHALL BE SOILD COPPER, CAPPED OVER, AND PLANARIZE FLAT.
- ALL 10 MIL FHS SHALL BE FILLED WITH TARSUTA AE332 CONDUCTIVE MATERIAL, CAPPED OVER, AND PLANARIZE FLAT.
- ELECTRONIC DATA IS EQUAL TO THE FINISHED LINE WIDTH.
- LPI SOLDER MASK COATING SHALL CONFORM TO IPC-SM-840, CLASS T. SMOBC. PRIMARY SIDE ONLY. COLOR GREEN.
- SILKSCREEN ON PRIMARY SIDE SHALL BE WHITE NON-CONDUCTIVE EPOXY INK.
REMOVE ANY SILKSCREEN ON EXPOSED PADS.
- GROUND EDGE PLATING DEFINED BY ARTWORK "EDGE PLATING" (MECHANICAL 9)
SHALL CONNECT GROUND FROM PRIMARY LAYER TO SECONDARY LAYER.
- GROUND FILL SHALL EXTEND TO BOARD EDGES UNLESS OTHERWISE NOTED.
EXPOSED COPPER ON BOARD EDGE SHALL BE ACCEPTABLE.
- MINIMUM LINE WIDTH AND SPACING IS .0045'', LINE WIDTHS ARE +/-1 MIL.
- LINE WIDTH AND SPACING FOR RF SHOULD BE 14 AND 6.5 MIL.
LINE WIDTH AND SPACING FOR PROBE SHALL BE 8 AND 4.5 MIL.
- ALL MATERIALS DESCRIBED IN THIS DOCUMENT/DRAWING SHALL BE IN COMPLIANCE WITH
AND CONTAIN NO SUBSTANCES RESTRICTED OR REQUIRING SPECIAL RECLAMATION UNDER
THE LATEST RoHS, WEEE OR ELV DIRECTIVES.



<div>UNLESS OTHERWISE SPECIFIED INTERPRET DRAWING PER ASME Y14.5 DO NOT SCALE THIS DRAWING</div> <div>NOTE: THIS DRW INCORPORATES THIRD ANGLE PROJECTION</div> <div></div> <div>MACOM Technology Solutions CONFIDENTIAL INFORMATION SUBJECT TO NDA</div> <div><small>The information contained in this document or material is the valuable and confidential property of MACOM Technology Solutions Holdings, Inc. and/or its subsidiaries or affiliates. Collectively, MACOM's, provided to you subject to a non-disclosure agreement between you and MACOM solely for use in supporting MACOM's business as and to the extent MACOM authorizes in writing from time to time. This information shall be held in strictest confidence and shall not be reproduced, published, disclosed to others, or used for any purpose except as and to the extent specifically authorized by MACOM in a separate written agreement. Permission is granted for reproduction, this legend must be included in any and all copies. This document or material shall be promptly returned to MACOM or destroyed upon request, completion of the use for which it was made available to recipient, or termination of MACOM's relationship with recipient, whichever first occurs.</small></div>	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES		<div> WWW.MACOM.COM</div>	
	TOLERANCES ON			
	DECIMALS	ANGLES	TITLE	
	.X ±.1 .XX ±.02 .XXX ±.005 .XXXX ±.0005	±0.5	PRINTED BOARD, MAAP-011378 EVAL BOARD	
UNLESS OTHERWISE SPECIFIED 63/ ALL OVER	MATERIAL	SIZE	DRAWING NO.	REVISION
FINISH	X	B	PT-0034689	A
		SCALE:	PACKAGE TYPE:	SHEET
		1/1	X	1 OF 1

X	MAAP-011378
NEXT ASSY	USED ON
APPLICATION	